EVERBEING

EB-6 Analytical Probe Station

Operation Manual

EVERBEING INT'L CORP
No.1,Jinshan 2nd St.,
Hsinchu, Taiwan 30080
TEL:886-3-6662000
FAX:886-3-6662200
probestation@me.com

Mar.2016

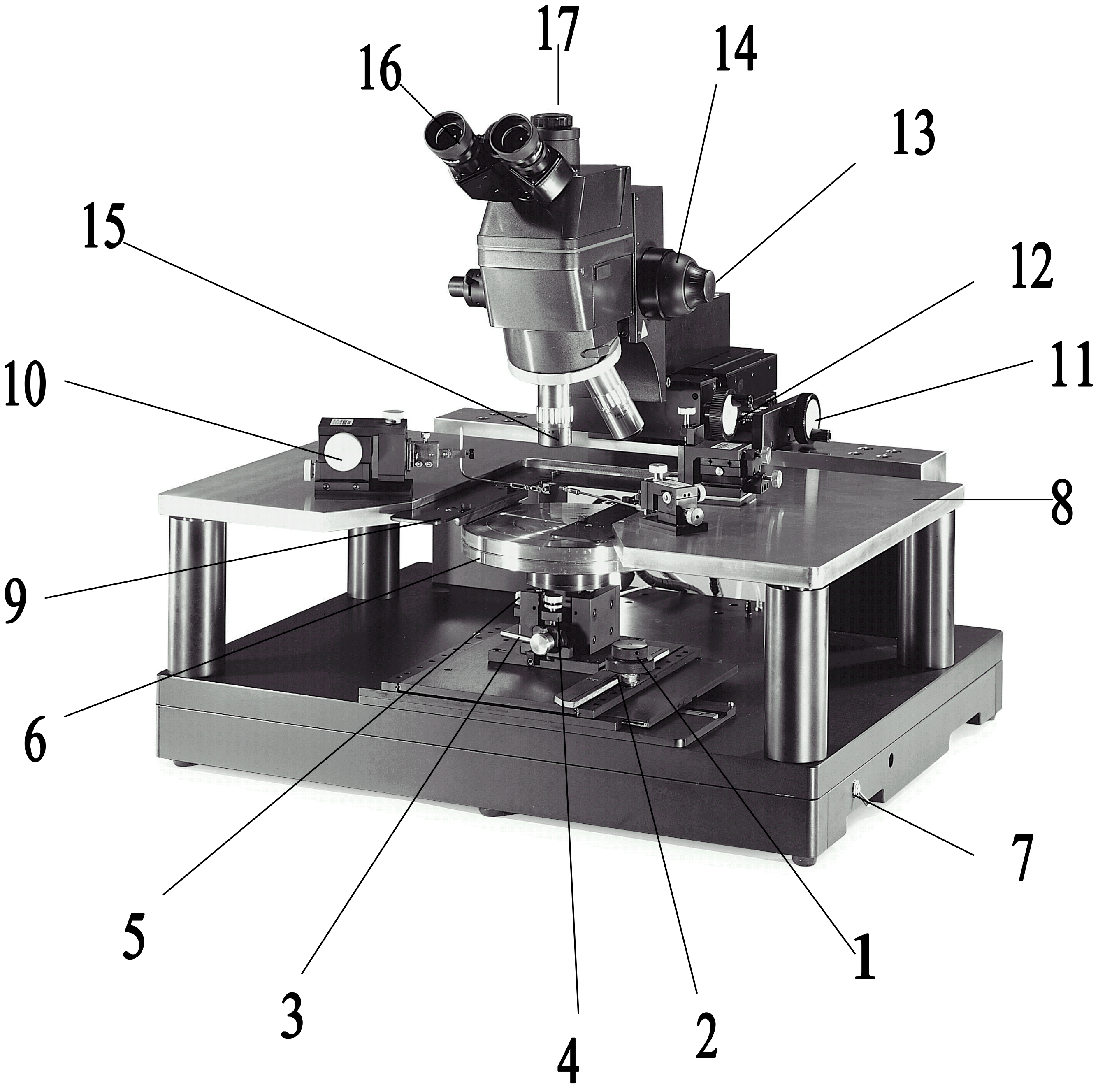
Table Of Contents

WARRANTY

This *EVERBEING* product is warranted to be free from defects in material and workmanship under normal use for a period of one year from the date of invoice.This limited warranty does not include cleaning, comsumables or damage caused by accident,neglet,misuse , any damage caused from service,maintenance,modification,or tempering by anyone other than Everbeing Authorized Representative.

EVERBEING INT'L CORP
No.1,Jinshan 2nd St.,
Hsinchu, Taiwan 30080
TEL:886-3-6662000
FAX:886-3-6662200
probestation@me.com

EB-8/EB-6 Pictorial
Analytical Probe Station



Operation Explanation

1.Chuck Stage X-Axis Control Knob
2.Chuck Stage Y-Axis Control Knob
3.Chuck Up/Down Lever
4.Chuck Up/Down High Adjustment
5.Chuck Up/Down Low Adjustment
6.Vacuum Chuck
7.Vacuum Chuck On/Off Switch
8.U- Shaped Platen
9.Probe Card Holder
10.Micropositioner
11.Microscope Stage X-Axis Knob
12.Microscope Stage Y-Axis Knob
13.Microscope Focus Fine Adjustment
14.Microscope Focus Coarse Adjustment
15.Microscope Objective
16.Microscope Eyepiece
17.Microscope CCD Port

Operation Procedures

/Micropositioner Probing

1. Lowering the chuck down by lever#3.
2. Moving the chuck out by turning Y-knob#2 to load the wafer on vacuum chuck#6.Turning on the vacuum switch #7 to suck the wafer securely. Moving the chuck back to probing position by turning Y-knob#2.Then raising the the chuck by lever#3.
3. Moving the chuck stage by X-knob #1 & Y-knob #2 to find the die for test.
4. Probing the tip onto the I/O pads from lower mag. objective to higher ones. (For customer using stereo microscope,turning the zoom knob to magnify the target).If the target is out of the view,moving the view by microscope X-knob#11 and Y-knob#12 to the target view area then probe.
5. Lowering the chuck down by lever#3.Moving the chuck stage by X-knob #1 & Y-knob #2 to the next die for test. Then raising the the chuck up by lever#3. to probe the tips with related distance onto the corresponding targets.

/Probe Card Probing

1. Lowering the chuck down by lever#3.
2. Moving the chuck out by turning Y-knob#2 to load the wafer on vacuum chuck#6.Turning on the vacuum switch #7 to suck the wafer securely. Moving the chuck back to probing position by turning Y-knob#2.Then raising the the chuck up by lever#3.
3. Moving the chuck stage by X-knob #1 & Y-knob #2 to find the die and I/O pads for test.
3. Rasising the chuck by turning knob #4 slowly and carefully to land the probe card tips onto the targets at the same time.If necessary,further up a little bit to make sure the tips are in good contact with the I/O pads at the same time.The mag. around 100X is suitable for probe card probing.
4. Lowering the chuck down by lever#3.Moving the chuck stage by X-knob #1 & Y-knob #2 to the next die for test. Then raising the the chuck up by lever#3 to probe the tips onto the corresponding I/O pads at the same time.

If there should be any question,please contact with local rep. first.If necessary,Everbeing direct.

Accessories

1. Thermal Chuck
2. Laser Cutter
3. RF Probe /Cables
4. Active ProbeLow Current Probe
5. Shielding Box
6. CCTV
7. Photomicrographics
8. Vibratiob Free Table
9. Probe Card Holder

Memo